


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/24/14728	
1.3 Title of PCN	ASE KaoHsiung (Taiwan) LQFP14x14 and LQFP20x20 package copper palladium bonding wire introduction on STM32H5x and STM32U5x listed products.	
1.4 Product Category	STM32H56x, STM32H57x STM32U53x, STM32U54x STM32U57x, STM32U58x STM32U59x, STM32U5Ax STM32U5Fx, STM32U5Gx	
1.5 Issue date	2024-07-19	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Direct Material: Bond Wire - Metallurgy (metallic composition/ raw material)	ASE Kaohsiung (TAIWAN)

4. Description of change

	Old	New
4.1 Description	Current Wire bonding material: - ASE KaoHsiung (Taiwan) gold wire	New Wire bonding material : - ASE KaoHsiung (Taiwan) copper palladium wire
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no impact on form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	To improve service
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	traceability ensured by ST Internal tools
------------------------	---

7. Timing / schedule

7.1 Date of qualification results	2024-07-12
7.2 Intended start of delivery	2024-10-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14728 MDG-GPM-RER2304-PCN13841 14224 14728 V3-ASE LQFP7 to 20 CuPd wire-RER report.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-07-19

9. Attachments (additional documentations)

14728 Public product.pdf
14728 MDG-GPM-RER2304-PCN13841 14224 14728 V3-ASE LQFP7 to 20 CuPd wire-RER report.pdf
14728 PCN14728_Additional information.pdf

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H563VIT6	
	STM32H563ZIT6	
	STM32H573VIT6	
	STM32H573ZIT3Q	
	STM32H573ZIT6	
	STM32U535VET6	
	STM32U535VET6Q	
	STM32U545VET6	
	STM32U545VET6Q	
	STM32U575VIT6	
	STM32U575VIT6Q	
	STM32U575ZIT6	
	STM32U575ZIT6Q	
	STM32U585VIT6	
	STM32U585VIT6Q	
	STM32U585ZIT6	
	STM32U585ZIT6Q	
	STM32U599VJT6	
	STM32U599VJT6Q	
	STM32U599ZJT6Q	
	STM32U5A5VJT6	
	STM32U5A5VJT6Q	
	STM32U5A5ZJT6	
	STM32U5A5ZJT6Q	
	STM32U5A9ZJT6Q	
	STM32U5G7VJT6Q	
	STM32U5G9VJT6Q	
	STM32U5G9ZJT6Q	
	STM32U599ZIT6Q	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2022 STMicroelectronics – All rights reserved